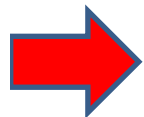
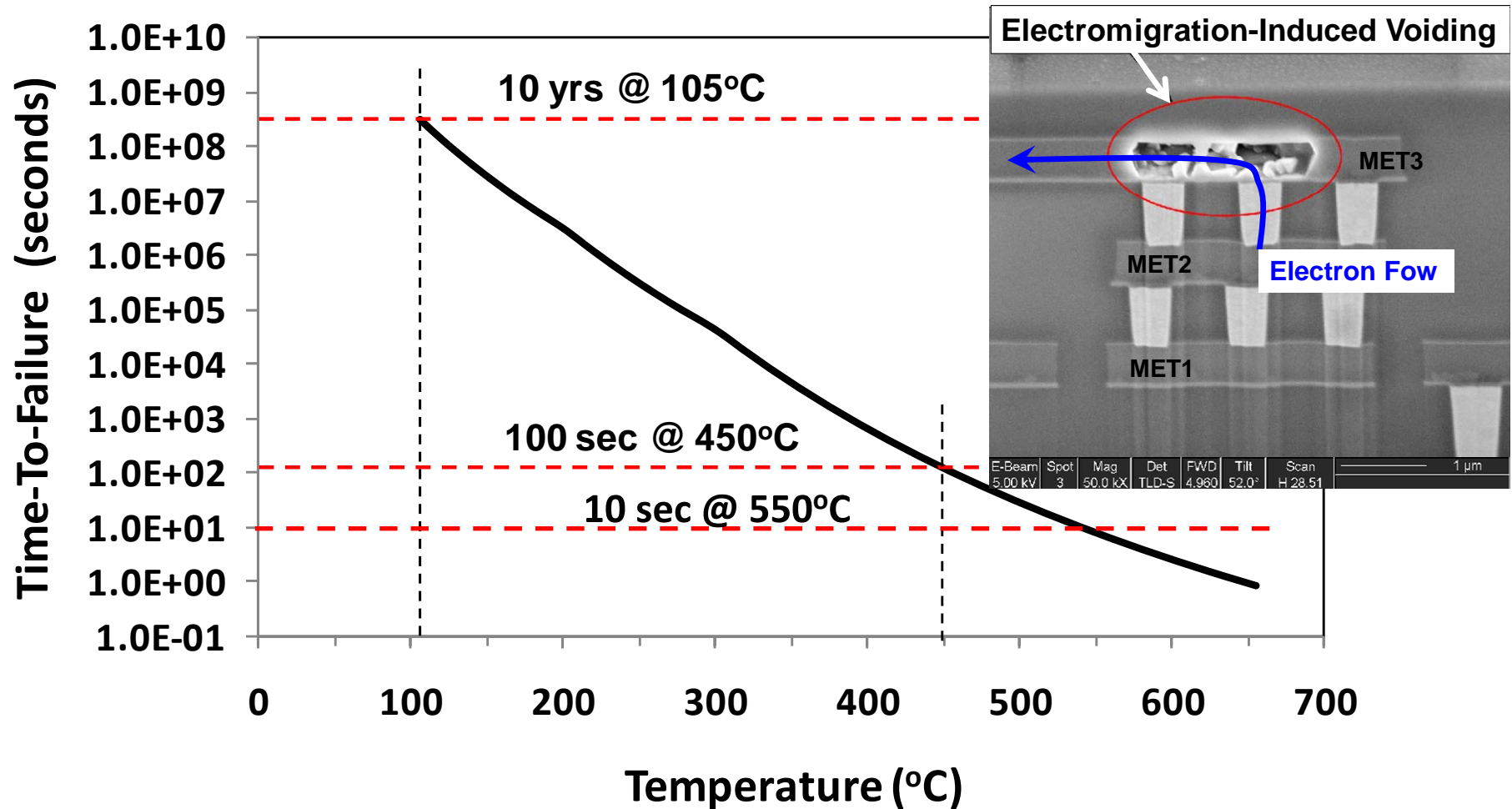

Power Devices and Critical Need for Thermal SOAs

**Power Device Reliability Often
Limited by Metal Migration**

T-SOA

Metal Electromigration Lifetime Versus Temperature



Note: Metal migration (normally requiring 10yrs at 105°C) occurs within ~100sec at 450°C or ~10sec at 550°C.

LDMOS Power Pulses-To-Failure

